

ELECTROLESS PLATING METHOD

Abstract

An electroless plating method of the present invention includes the steps of preparing a substrate having an insulating body and a conductive pattern formed thereon, adhering a catalytic metal serving as a catalyst of an electroless plating onto the insulating body and the conductive pattern, forming selectively a protection film or an oxidizing agent used to oxidize the catalytic metal on the catalytic metal in a space portion between the conductive pattern, and forming selectively a metal layer on the conductive pattern by the electroless plating.